

Final Product/Process Change Notification Document #: FPCN24642Z Issue Date: 01 Dec 2022

Title of Change:	Addition of King Yuan Electronics Corp. (KYEC) as Final Test and Packing location.		
Proposed Changed Material First St Date:	08 Jun 2023 or earlier if approved by customer		
Current Material Last Order Date:	N/A Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.		
Current Material Last Delivery Date	: N/A The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory		
Product Category:	Active components – Integrated circuits		
Contact information:	Contact your local onsemi Sales Office		
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Sample Availability Date:	N/A		
PPAP Availability Date:	12 Dec 2022		
Additional Reliability Data:	Contact your local onsemi Sales Office or Shiela.Crosby@onsemi.com		
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com.		
Change Category	·		
Category	Type of Change		
Test Flow	Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor		
Description and Purpose:			
Addition of KYEC, Taiwan as Final Test a	nd Packing location for product NCV78763DQ0AR2G to improve tester capacity balancing and loading.		
There are no material nor product mark	ing changes as a result of this PFCN.		
Reason / Motivation for Change:	apacity improvement		
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.		

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Sites Affected:				
onsemi Sites		External Foundry/Subcon Sites		
None		KYEC, Taiwan		
Marking of Parts/ Traceability of Change:	Changed material can be identified by lot code			
Reliability Data Summary:				
Not applicable. No change in material.				
Flactrical Characteristics Summary:				

QC ambient correlation data between the source location (OSPI, Philippines) and the target location (KYEC, Taiwan) is provided with this FPCN. The correlation procedure used, is identical to previous PCN's covering the release of additional tester platforms: full parametric correlation was performed and for every test the shift was evaluated. Any parameter that exceeds the allowable shift is independently analyzed and explained..

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Current Part Number	New Part Number	Qualification Vehicle
NCV78763DQ0AR2G	NA	NCV78763DQ6AR2G

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